

Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS 389	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:09	
2	BRS 1178	702/176,177,178,184,187.cc 1s.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:19	
3	BRS 0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 same process\$3 with parameter\$1 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:19	
4	BRS 65	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (conditio\$1 or status or state\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	

Type	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS 6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condicition\$1 or status or state\$1) with equipment\$1 and (estimat\$3 or validat\$3 or evaluat\$3 or predict\$3) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	
6	BRS 6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condicition\$1 or status or state\$1) with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	

Type	Hits	Search Text	DBs	Time Stamp	Comments
		(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1 with parameter\$1 and process\$3 with parameter\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
7	BRS 0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
8	BRS 8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
9	BRS 65	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	

Type	Hits	Search Text	DBs	Time Stamp	Comments
10	18	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	
11	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) with measur\$6	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:32	

Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS 17	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
13	BRS 4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	

Type	Hits	Search Text	DBS	Time Stamp	Comments
14	9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:35	
15	76	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6)	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS 51	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6)	US-PPGPUB; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	
17	BRS 24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

Type	Hits	Search Text	DBS	Time Stamp	Comments
18	BRS 15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with qualit\$3 and (records\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (records\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	

Type	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS 2	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and statistic\$4 with (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	
20	BRS 4	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:38	

Type	Hits	Search Text	DBS	Time Stamp	Comments
21	BRS 24	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3) (record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3) and statistic\$4	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	
22	BRS 14		US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	

Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS 3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and t- test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
24	BRS 18	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6 and optimiz\$5 with performance	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:13	
25	BRS 32542	(determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomal\$3 or problem\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:15	

Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS 18	(determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomaly\$3 or problem\$1) and optimiz\$3 with qualit\$3 with performance\$1 with product\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:17	
27	BRS 0	(determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomaly\$3 or problem\$1) and select\$3 with process\$3 with parameter\$1 same optimiz\$3 with qualit\$3 with performance\$1 with product\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:18	

Type	Hits	Search Text	DBs	Time Stamp	Comments
28	BRS	702/176, 177, 178, 183, 184, 187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/10/28 15:20	
29	BRS	(700/12, 14, 17, 19, 108, 117, 21, 174, 175, 176, 178, 180.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/10/28 15:19	
30	BRS	702/176, 177, 178, 183, 184, 187.ccls. or 700/12, 14, 17, 19, 108, 117, 121, 174, 175, 176, 178, 180.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/10/28 15:23	
31	IS&R 2	("6745094") . PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/10/28 15:22	
32	BRS 0	"6745094".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/10/28 15:23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS 379	(702/176, 177, 178, 183, 184, 187.cc1s. or 700/12, 14, 17, 19, 108, 117, 121, 174, 175, 176, 178, 180.cc1s .) and (determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomalous\$3 or problem\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:24	
34	BRS 21	(702/176, 177, 178, 183, 184, 187.cc1s. or 700/12, 14, 17, 19, 108, 117, 121, 174, 175, 176, 178, 180.cc1s .) and (determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomalous\$3 or problem\$1) with process\$3 with parameter\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:25	

Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS 94	(702/176,177,178,183,184,187.cc1s. or 700/12,14,17,19,108,117,121,174,175,176,178,180.cc1s.) and (determin\$3 or detect\$3 or monitor\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (defect\$1 or error\$1 or fail\$4 or malfunction\$2 or anomaly\$3 or problem\$1)	US-PGPUB	2005/10/28 15:25	
36	BRS 74	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	

Type	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS 7	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and (estimat\$3 or validate\$3 or evaluat\$3 or predict\$3) with qualit\$3	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	
38	BRS 7	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 with parameter\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	

Type	Hits	Search Text	DBs	Time Stamp	Comments
39	BRS 0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1 with parameter\$1 and process\$3 with parameter\$1 and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
40	BRS 9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
41	BRS 74	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with quality\$3 and (condiction\$1 or status or state\$1) with equipment\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	

Type	Hits	Search Text	DBs	Time Stamp	Comments
42	BRS 26	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	
43	BRS 8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) with measur\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:32	

Type	Hits	Search Text	DBs	Time Stamp	Comments
44	BRS 25	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3)	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
45	BRS 5	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	

Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS 10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
47	BRS 10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (condiction\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:35	

Type	Hits	Search Text	DBs	Time Stamp	Comments
48	BRS 87	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	
49	BRS 57	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

Type	Hits	Search Text	DBS	Time Stamp	Comments
50	BRS 29	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

Type	Hits	Search Text	DBs	Time Stamp	Comments
51	BRS 19	<p>(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1 with process\$3</p>	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	

Type	Hits	Search Text	DBs	Time Stamp	Comments
52	BRS 3	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and statistic\$4 with (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	
53	BRS 5	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:38	

Type	Hits	Search Text	DBS	Time Stamp	Comments
54	28	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3) (record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1) with product\$1 and (analyz\$3 or analys\$3) and statistic\$4	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	
55	17		US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	

Type	Hits	Search Text	DBs	Time Stamp	Comments
56	9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and t-test\$3	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
57	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and t-test\$3 and process\$3 with parameter\$1	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
58	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and t-test\$3 and process\$3 with parameter\$1 and optimiz\$3	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	

U	1	Document ID	Issue Date	Page S	Title	Current OR	Current XRef	Retrieval 1 Classif
1		US 2005020365	20050915	18	System and method for scheduling manufacturing jobs for a semiconductor manufacturing tool	700/100	700/108	700/108
2	X	US 2005019772	20050908		FEATURE TARGETED INSPECTION	700/110	700/121	700/121
3	X	US 2005017726	20050811	26	Method for dynamic sensor configuration and runtime execution	700/121		
4	X	US 2005017726	20050811	3 A1	System and method for monitoring wafer furnace production efficiency	700/108	700/108	
5	X	US 2005017162	20050804	7 A1	Method and apparatus for monitoring tool performance	700/121	700/121	
6	X	US 2005017162	20050804	6 A1	System, method, and medium for monitoring performance of an advanced process control system	700/108	700/108	

U	1	Document ID	Issue Date	Page S	Title	Current OR	Current XRef	Retrieval 1 Classif
	X	US 2005015991	20050721		Method and apparatus for automatic sensor installation	702/104	700/121	700/121
7	X	US 2005013773	20050623		Integrated circuit card system and application loading method	700/121		
8	X	US 2005012509	20050609		Method and apparatus for evaluating processing apparatus status and predicting processing result	700/108	438/14; 700/121	700/108; 700/121
9	X	US 2005012251	20050609		System and method for process variation monitor	356/237.2	382/145; 700/121	700/121
10	X	US 2005009092	20050428		Method for monitoring a batch system	700/109	257/E21.5 25; 700/121	700/121
11	X	US 2005009092	20050428	3 A1				

U	1	Document ID	Issue Date	Page	Title	Current OR	Current XRef	Retrieval Classif
					Test circuit, semiconductor product wafer having the test circuit, and method of monitoring manufacturing process using the test circuit	700/108	438/14	700/108
12	X	US 2005009092	20050428		Technique for evaluating a fabrication of a semiconductor component and wafer	700/90	700/108	700/108
13	X	US 2005008593	20050421		System and method for implementing logic control in programmable controllers in distributed control systems	700/19; 700/20; 700/276; 700/277; 700/278; 700/86; 700/87	700/19	
14	X	US 2005008592	20050421		Process parameter based I/O timing programmability using electrical fuse elements	702/176	702/176	
15	X	US 2005007583	20050407					

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16	X	US 2005007103	20050331	1 A1	Algorithms tunning for dynamic lot dispatching in wafer and chip probing	700/101	700/100; 700/121	700/121
17	X	US 2005005512	20050310	1 A1	System and method for effective field loss analysis for semiconductor wafers	700/110	700/121	700/121
18	X	US 2005005426	20050310	8 A1	Methods for detecting transitions of wafer surface properties in chemical mechanical polishing for process status and control	451/5	700/121	700/121
19	X	US 2005004983	20050303	4 A1	Non-invasive system and method for diagnosing potential malfunctions of semiconductor equipment components	702/183	702/183	

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20	X	US 2005004974 0 A1	20050303		Method, system and program product providing a configuration specification language having clone latch support	700/121		700/121
21	X	US 2005003854 4 A1	20050217	7	MANAGEMENT SYSTEM OF MONITOR WAFERS	700/108	700/108; 700/80	700/121; 700/121
22	X	US 2005002748 2 A1	20050203		Method for estimating the quality of wood chips	702/183		702/183
23	X	US 2005002738 8 A1	20050203		Reducing asymmetrically deposited film induced registration error	700/121		700/121
24	X	US 2005001089 0 A1	20050113	22	Design-based monitoring	716/19	700/121; 716/21; 716/4	700/121
25	X	US 2004026042 0 A1	20041223	51	Processing method and processing system	700/121		700/121

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26	X	US 2004025476	20041216		Operation monitoring method for treatment apparatus	702/182	702/183	702/183
27	X	US 2004025466	20041216		Automatic recognition of locator die in partial wafermap process	700/121	382/151	700/121
28	X	US 2004022540	20041111		Computer-implemented method and carrier medium configured to generate a set of process parameters and/or a list of potential causes of deviations for a lithography process	700/121	700/121	
29	X	US 2004019928	20041007		Method for determining a preceding wafer, method for determining a measuring wafer, and method for adjusting the number of wafers	700/121	700/121	

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		US 2004018130	20040916		Relatively unique ID in integrated circuit	700/115	380/44; 700/121	700/121
30	X	US 2004017215	20040902		Sorting a group of integrated circuit devices for those devices requiring special testing	700/121		
31	X	US 2004016765	20040826		Production managing system of semiconductor device	700/121		700/121
32	X	US 2004014813	20040729		Management supporting apparatus, management supporting system, management supporting method, management supporting program, and a recording medium with the program recorded therein	700/121		700/121
33	X	US 2004014813	20040729			702/188	702/184	702/184
34	X	US 2004013329	20040708		Defect alarm system and method	700/110	700/121	700/121

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35	X	US 2004011705	20040617		Configuration and method for detecting defects on a substrate in a processing tool	700/121	700/110	700/121
36	X	US 2004011117	20040610		In-situ randomization and recording of wafer processing order at process tools	700/121		
37	X	US 2004010702	20040603		Fabrication system and fabrication method	700/121		700/121
38	X	US 2004008807	20040506		Aligner evaluation system, aligner evaluation method, a computer program product, and a method for manufacturing a semiconductor device	700/121	700/121	
39	X	US 2004005945	20040325		Correlating an inline parameter to a device operation parameter	700/121	257/E21.5 25	700/121

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40	X	US 2004003947	20040226	3 A1	Integrated circuit profile value determination	700/121		700/121
41	X	US 2004002902	20040212	9 A1	Error reduction in semiconductor processes	430/30	355/44; 355/52; 355/56; 430/22; 430/311;	700/121
42	X	US 2004001525	20040122	6 A1	Feedback method utilizing lithographic exposure field dimensions to predict process tool overlay settings	700/121	700/65; 702/122	
43	X	US 2004000640	20040108	4 A1	Permanent chip ID using FerAM	700/115	700/121	700/121
44	X	US 2003023658	20031225	6 A1	Method for failure analysis and system for failure analysis	700/110	700/121	700/121

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45	X	US 2003022547	20031204	5 A1	Method and system for estimating microelectronic fabrication product yield	700/121	700/108	700/108; 700/121
46	X	US 2003022070	20031127	8 A1	Integrated equipment set for forming shallow trench isolation regions	700/121	438/690	700/121
47	X	US 2003021734	20031120	3 A1	Manufacturing method and apparatus to avoid prototype-hold in ASIC/SOC manufacturing	716/4	700/121	700/121
48	X	US 2003021246	20031113	9 A1	METHOD FOR AUTOMATICALLY CONTROLLING DEFECT - SPECIFICATION IN A SEMICONDUCTOR MANUFACTURING PROCESS	700/121	438/14; 700/110	700/121
49	X	US 2003020005	20031023	6 A1	Semiconductor device analysis system	702/183		702/183

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		US 2003019910	20031023	8 A1	Method of monitoring and/or controlling a semiconductor manufacturing apparatus and a system therefor	438/14	118/663; 156/345.24; 257/E21.5 25; 700/121	700/121
51	X	US 2003019155	20031009	0 A1	Method for using data regarding manufacturing procedures integrated circuits (IC's) have undergone, such as repairs, to select procedures the IC's undergo, such as additional repairs	700/121	700/121	
52	X	US 2003018753	20031002	5 A1	Throughput analysis system and method	700/108	700/104; 700/111	700/108
53	X	US 2003018207	20030925	9 A1	System and method to provide measurement capabilities for both single-ended and differential signals with software switching	702/177		702/177

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		US 2003017189	20030911		Method and system for graphical evaluation of IDQ measurements	702/183		702/183
54	X	6 A1			Semiconductor manufacturing apparatus, management apparatus, therefore, component management apparatus therefore, and semiconductor wafer storage vessel transport apparatus	700/108	702/182; 702/187	700/108; 702/187
55	X	US 2003017183	20030911	52	Semiconductor manufacturing apparatus and its diagnosis apparatus and operating system	700/108	700/121	700/108; 700/121
56	X	US 2003016321	20030828	7 A1	Method for diagnosing life of manufacturing equipment using rotary machine	702/184		702/184
57	X	US 2003015405	20030814	2 A1				

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		US 2003015399	20030814	5 A1	Semiconductor manufacturing system and control method thereof	700/101	700/121	700/121
58	X	US 2003014954	20030807	7 A1	Method for diagnosing failure of a manufacturing apparatus and a failure diagnosis system	702/183	702/183	
59	X	US 2003013983	20030724	9 A1	Method of sorting a group of integrated circuit devices for those devices requiring special testing	700/115	700/109; 700/116; 700/121	700/121
60	X	US 2003013529	20030717	5 A1	Defect source identifier with static manufacturing execution system	700/108	700/108; 700/110; 700/117; 700/121	700/121
61	X	US 2003013529	20030717	5 A1				

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					Apparatus and method for automatically controlling semiconductor manufacturing process in semiconductor factory automation system			
62	X	US 2003010994	20030612	5 A1	SYSTEM AND METHOD FOR MODIFYING ENCLOSED AREAS FOR ION BEAM AND LASER BEAM BIAS EFFECTS	700/95	700/109; 700/121	700/121
63	X	US 2003010554	20030605	7 A1	Method and system of monitoring apparatuses of manufacturing IC	700/121	438/4	700/121
64	X	US 2003010097	20030529	0 A1	AC defect detection and failure avoidance power up and diagnostic system	700/108	700/109; 700/121	700/108; 700/121
65	X	US 2003006548	20030403	4 A1	Automatic production quality control method and system	702/187		702/187
66	X	US 2003006091	20030327	6 A1		700/121	700/109	700/121

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		US 2003005552	20030320	15	User configurable multivariate time series reduction tool control method	257/E21.525;	700/108;700/175;	700/108;700/175
67	X	3 A1			Management system and management method of semiconductor exposure apparatuses	700/108;700/51;	700/83;	702/185
68	X	US 2003003730	20030220	9 A1	Method and system for manufacturing semiconductor devices	716/21	700/121	700/121
69	X	US 2003003304	20030213	23	Method and system for manufacturing semiconductor devices	700/121	716/21	700/121
70	X	US 2003001840	20030123	23	Method and system for manufacturing semiconductor devices	700/121	716/21	700/121
71	X	US 2003001414	20030116	6 A1	Dangerous process/pattern detection system and method, danger detection program, and semiconductor device manufacturing method	700/121		700/121

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		US 2003001414	20030116	18	Integration of fault detection with run-to-run control	700/121	700/108; 700/110	700/108; 700/121
72	X	5 A1			Method and apparatus for determining end-point in a chamber cleaning process	702/184		
73	X	US 2002019868	20021226	8	Dynamic metrology schemes and sampling schemes for advanced process control in semiconductor processing	700/108	257/E21.5 25; 700/121; 700/97	700/108; 700/121
74	X	US 2002019389	20021219	18	Method for continuous, non lot-based integrated circuit manufacturing	700/121	700/121	
75	X	US 2002018388	20021205		Systems and methods for metrology recipe and model generation	700/115	700/121	700/121
76	X	US 2002016563	20021107	24	Device and method of selecting photomask manufacturer based on received data	700/121		700/121
77	X	US 2002014342	20021003			700/121		700/121

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		US 2002012381	20020905		Production managing system of semiconductor device	700/121		700/121	
78	X	US 2002011759	20020815		Failure analysis device and failure analysis method	702/82	700/108; 700/109; 700/110	700/108	
80	X	US 2002010766	20020808		Maintenance system for analyzing instrument	702/184		702/184	
81	X	US 2002010356	20020801		Methods and systems for determining a composition and a thickness of a specimen	700/121		700/121	
82	X	US 2002010356	20020801		Method of manufacturing a semiconductor device and manufacturing system	700/121		700/121	

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					Method for using data regarding manufacturing procedures integrated circuits (IC's) have undergone, such as repairs, to select procedures the IC's will undergo, such as additional repairs	700/121	700/121	
83	X	US 2002008274	20020627	0 A1	Deterioration diagnostic method and equipment thereof	702/183	702/183	
84	X	US 2002007287	20020613	8 A1	Method and apparatus for designing integrated circuits and storage medium for storing the method	700/121	700/121	
85	X	US 2002006898	20020606	9 A1	User configurable multivariate time series reduction tool control method	700/108	257/E21.5 25; 700/51	700/108
86	X	US 2002006216	20020523	15 2 A1				

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		US 2002005901	20020516		Method of manufacturing semiconductor devices	700/121	257/E21.5 25;	700/121
87	X	2 A1			Fault analyzing device for semiconductor	700/110	700/109; 700/117;	700/117; 700/121
88	X	US 2002005901	20020516	0 A1	Fault detection and virtual sensor methods for tool fault monitoring	700/111	700/117; 700/175;	700/117; 700/175;
89	X	US 2002005580	20020509	1 A1	Remote diagnosing system for semiconductor manufacturing equipment and a remote diagnosing method	700/178	700/178	700/178
90	X	US 2002003544	20020321	35 7 A1	System and method for monitoring and controlling gas plasma processes	702/188	257/E21.5 438/14; 700/108; 700/121; 700/2; 702/183	700/108; 700/121; 702/183
91	X	US 2002002625	20020228	1 A1	System and method for monitoring and controlling gas plasma processes	700/67	700/121; 700/68	700/121
92	X	US 2001005183	20011213	9 A1	DIFFERENTIAL PROCESS CONTROL METHOD	700/121		700/121

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